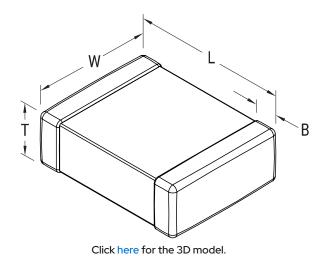


## CBR02C808B3GAC

**General Information** 

Series

CBR-SMD RF COG, Ceramic, 0.8 pF, +/-0.1 pF, 25 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0201



Style SMD Chip Description SMD, Fixed, RF, Ultra High Q, Low ESR, Class I Features Ultra High Q, Low ESR, Class I RoHS Yes Termination Tin Marking No AEC-Q200 No Typical Component Weight 0.3 mg Notes Solder Reflow Only. Shelf Life 78 Weeks MSL 1

CBR-SMD RF COG

Dimensions	
Chip Size	0201
L	0.6mm +/-0.03mm
W	0.3mm +/-0.03mm
т	0.3mm +/-0.03mm
В	0.15mm +/-0.05mm

15000

T&R, 180mm, Plastic Tape

Packaging Specifications	
Packaging	

Packaging Packaging Quantity Specifications Capacitance 0.8 pF Tolerance +/-0.1 pF Voltage DC 25 VDC **Dielectric Withstanding Voltage** 62.5 VDC -55/+125°C **Temperature Range** COG Temp. Coefficient 0.24% **Dissipation Factor** 0% Loss/Decade Hour Aging Rate Insulation Resistance 10 GOhms **Quality Factor** 416

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